



Material Content Data Sheet



Halogen-Free

Sales Product Name	IPP052N08N5	Issued	17. February 2022
MA#	MA005698676		
Package	PG-TO220-3-1	Weight*	2035.53 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	1.810	0.09	0.09	889	889
leadframe	inorganic material	phosphorus	7723-14-0	0.245	0.01		120	
	non noble metal	iron	7439-89-6	0.816	0.04		401	
	non noble metal	copper	7440-50-8	815.335	40.07	40.12	400551	401072
wire	non noble metal	aluminium	7429-90-5	7.522	0.37	0.37	3695	3695
encapsulation	inorganic material	zinc oxide	1314-13-2	5.960	0.29		2928	
	miscellaneous	miscellaneous	-	23.841	1.17		11712	
	plastics	epoxy resin	-	89.404	4.39		43922	
	inorganic material	silicon dioxide	60676-86-0	476.820	23.42	29.27	234249	292811
lead finish	non noble metal	tin	7440-31-5	21.462	1.05	1.05	10544	10544
plating	inorganic material	phosphorus	7723-14-0	0.001			1	
	non noble metal	nickel	7440-02-0	0.244	0.01	0.01	120	121
solder	non noble metal	tin	7440-31-5	0.037			18	
	noble metal	silver	7440-22-4	0.046			23	
	non noble metal	lead	7439-92-1	1.754	0.09	0.09	862	903
heatspreader	inorganic material	phosphorus	7723-14-0	0.177	0.01		87	
	non noble metal	iron	7439-89-6	0.590	0.03		290	
	non noble metal	copper	7440-50-8	589.466	28.96	29.00	289588	289965
*deviation	< 10%	Sum in total:				100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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